

GT23SC55460

**Reader/Writer IC conform to ISO/IEC 14443A and widely used in
NFC payment environment**

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1. Features

- Conform to ISO/IEC 14443A
- Highly integrated analog circuitry to demodulate and decode responses
- 13.56MHz operating frequency
- 106 kbit/s data transfer rate
- I²C/SPI/UART bus interface for host connection
- Programmable Timer
- Internal oscillator
- FIFO buffer handles 64 byte send and receive
- Typically operating distance in Reader/Writer mode up to 50mm depending on the antenna size and tuning
- 2.5V to 3.3V power supply
- CRC coprocessor

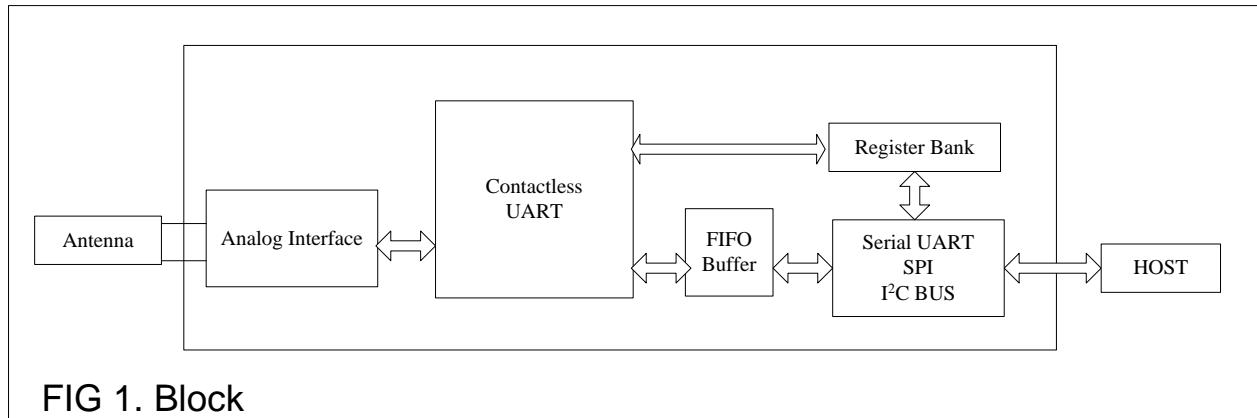
2. General Description

GT23SC55460 is a highly integrated reader/writer IC for contactless communication at 13.56 MHz and supports ISO/IEC 14443 A mode.

GT23SC55460's internal transmitter is able to drive a reader/writer antenna designed to communicate with ISO/IEC 14443 A cards and transponders without additional active circuitry. The receiver module provides a robust and efficient implementation for demodulating and decoding signals from ISO/IEC 14443 A compatible cards and transponders. The digital module manages the complete ISO/IEC 14443 A framing and error detection (parity and CRC) functionality.

GT23SC55460 supports the lowest power supply minimum to 2.5V.

3. Block diagram



4. Package

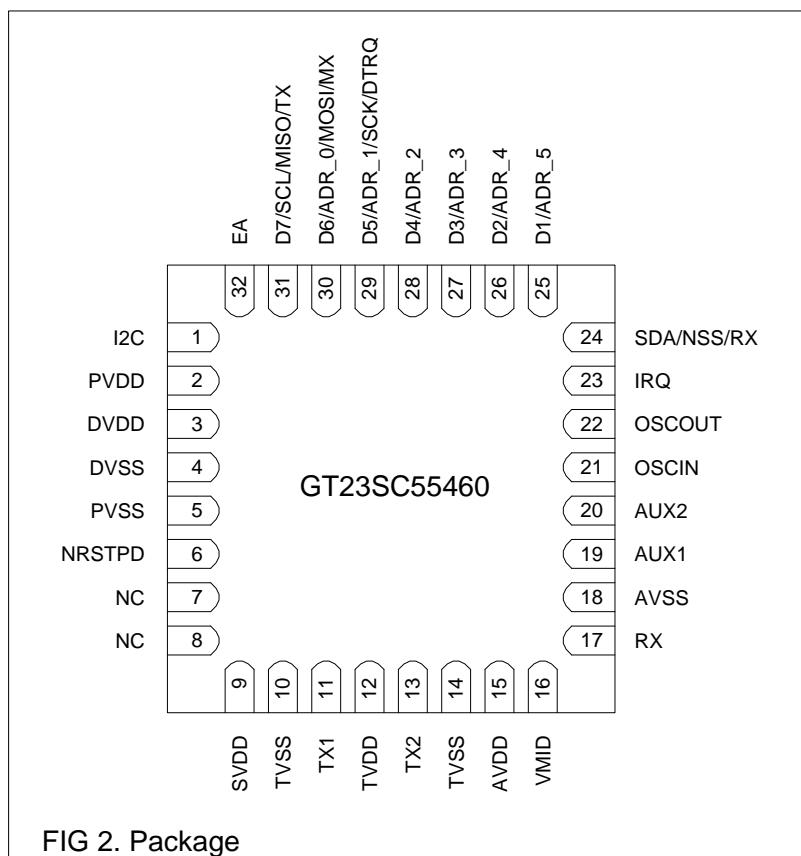
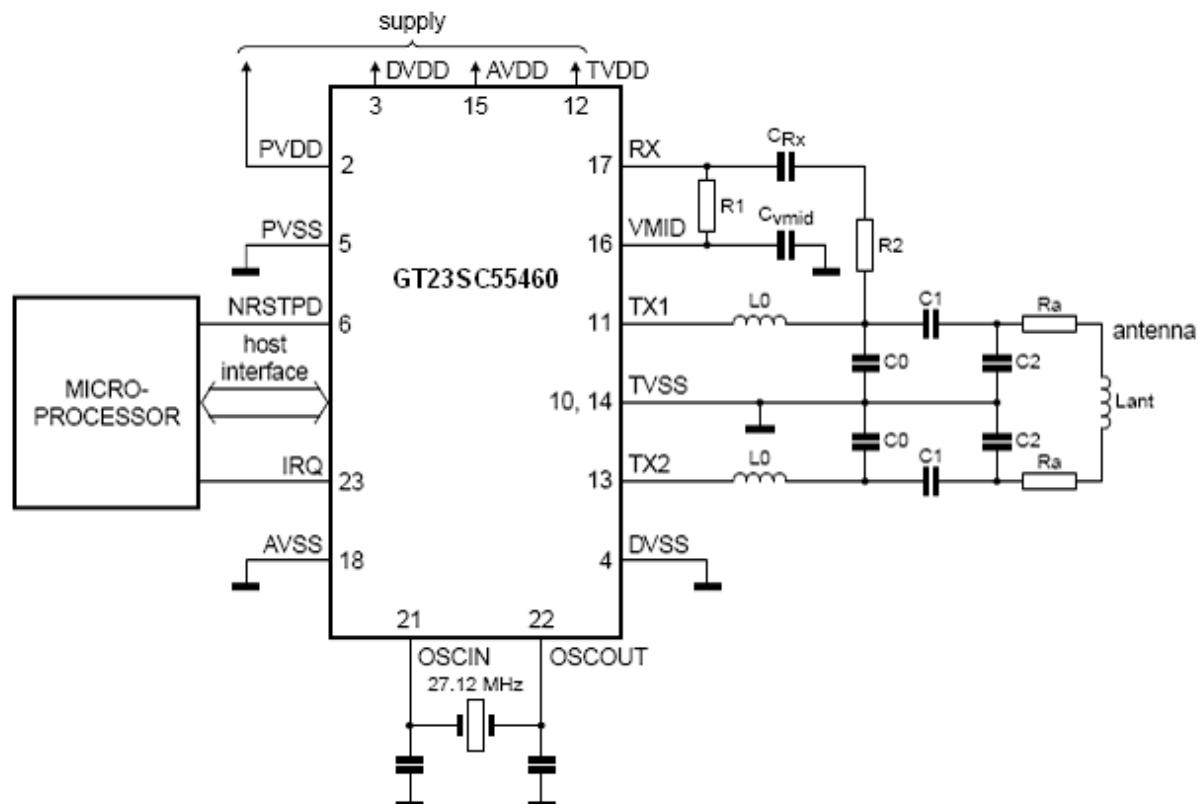


FIG 2. Package

5. Pin Description

| Pin Id | Name | Function |
|--------|------------------|---|
| 1 | I ² C | I2C-bus enable input |
| 2 | PVDD | pin power supply |
| 3 | DVDD | digital power supply |
| 4 | DVSS | digital ground |
| 5 | PVSS | pin power supply ground |
| 6 | NTSTPD | reset and power-down input |
| 7 | NC | NC |
| 8 | NC | NC |
| 9 | SVDD | Internal power supply |
| 10 | TVSS | transmitter output stage 1 ground |
| 11 | TX1 | transmitter 1 modulated 13.56 MHz energy carrier output |
| 12 | TVDD | transmitter power supply |
| 13 | TX2 | transmitter 2 modulated 13.56 MHz energy carrier output |
| 14 | TVSS | transmitter output stage 2 ground |
| 15 | AVDD | analog power supply |
| 16 | VMID | internal reference voltage |
| 17 | RX | RF signal input |
| 18 | AVSS | analog ground |
| 19 | AUX1 | auxiliary outputs for test purposes |
| 20 | AUX2 | auxiliary outputs for test purposes |
| 21 | OSCIN | crystal oscillator inverting amplifier input |
| 22 | OSCOUT | crystal oscillator inverting amplifier output |
| 23 | IRQ | interrupt request output |
| 24 | SDA | I2C-bus serial data line input/output |
| 25 | D1 | test port |
| | ADR_5 | I2C-bus address 5 input |
| 26 | D2 | test port |
| | ADR_4 | I2C-bus address 4 input |
| 27 | D3 | test port |
| | ADR_3 | I2C-bus address 3 input |
| 28 | D4 | test port |
| | ADR_2 | I2C-bus address 2 input |
| 29 | D5 | test port |
| | ADR_1 | I2C-bus address 1 input |
| 30 | D6 | test port |
| | ADR_0 | I2C-bus address 0 input |
| 31 | D7 | test port |
| | SCL | I2C-bus clock input/output |
| 32 | EA | external address input for coding I2C-bus address |

6. Typical Application



7. Limiting Values

| Symbol | Parameter | Conditions | Min | Max | Unit |
|-----------------------|---------------------------------|--|-------------------------------|-------------------------------|------|
| V _{DDA} | analog supply voltage | V _{DDA} | -0.5 | +4.0 | V |
| V _{DDD} | digital supply voltage | V _{DDD} | -0.5 | +4.0 | V |
| V _{DD(PVDD)} | PVDD supply voltage | V _{DD(PVDD)} | -0.5 | +4.0 | V |
| V _{DD(TVDD)} | TVDD supply voltage | V _{DD(TVDD)} | -0.5 | +4.0 | V |
| V _{DD(SVDD)} | SVDD supply voltage | V _{DD(SVDD)} | -0.5 | +4.0 | V |
| V _I | input voltage | all input pins except pin RX | V _{SS(PVSS)} -0.5 | V _{DD(SVSS)} +0.5 | V |
| P _{tot} | total power dissipation | per package; and VDDD in shortcut mode | | 200 | mW |
| T _j | junction temperature | | | 100 | °C |
| V _{ESD} | electrostatic discharge voltage | HBM; 1500 Ω, 100pF; | | 2000 | V |
| | | MM; 0.75μH, 200pF; | | | |

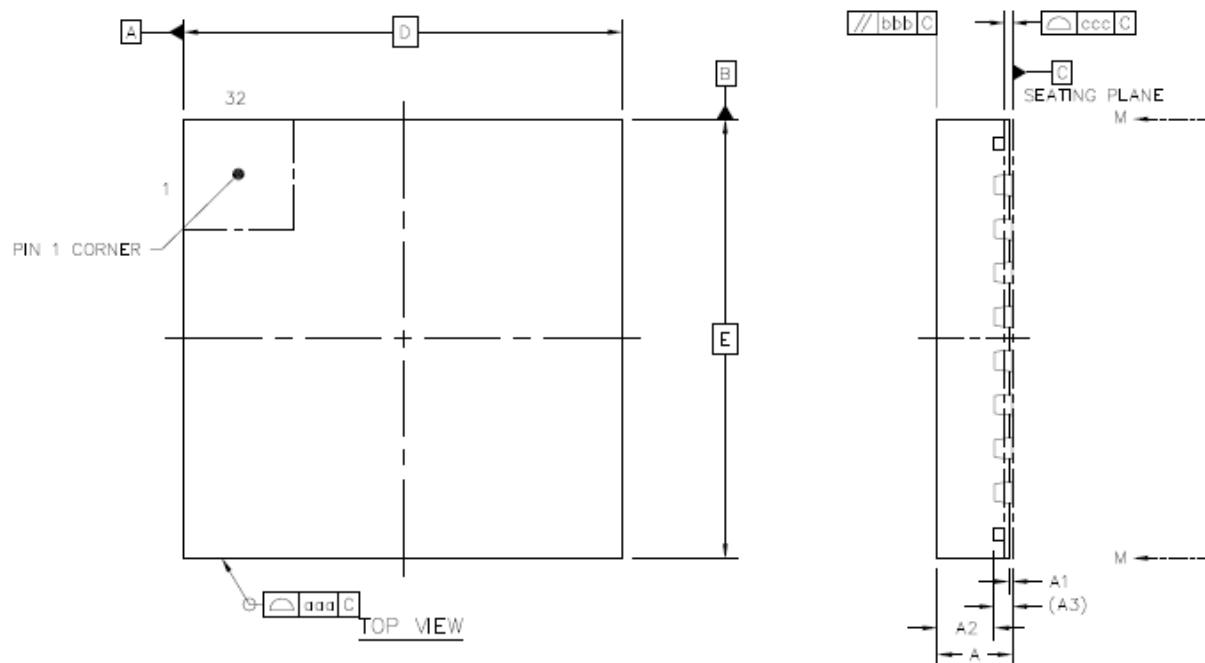
8. Operating Conditions

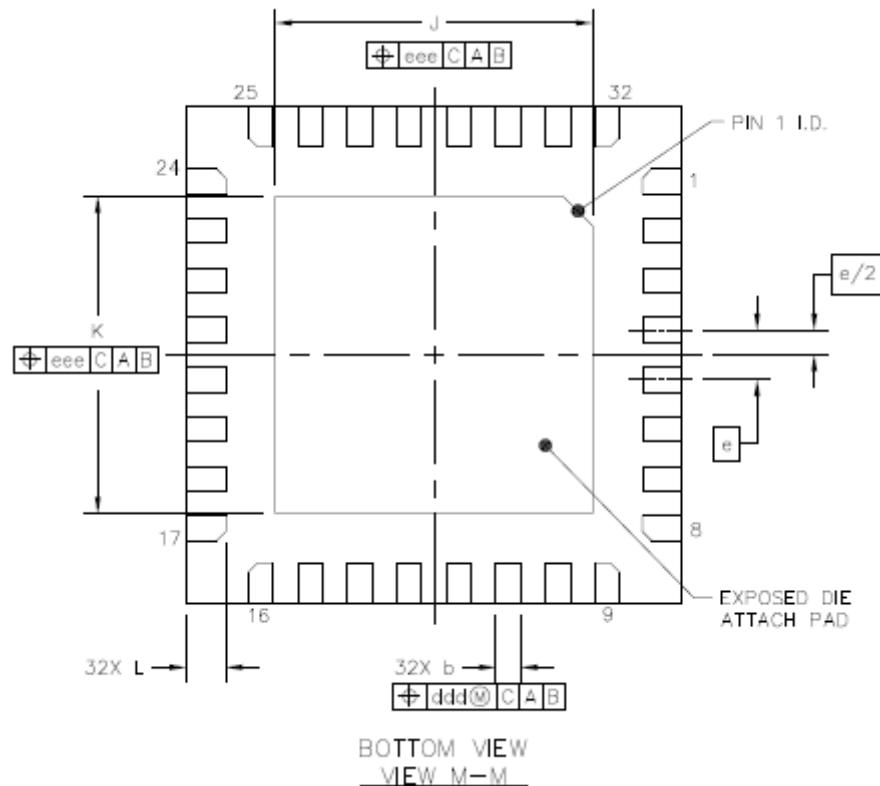
| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-----------------------|------------------------|---|-----|-----|-----|------|
| V _{DDA} | analog supply voltage | V _{DD(PVDD)} ≤ V _{DDA} = V _{DDD} = V _{DD(TVDD)} , V _{SSA} = V _{SSD} = V _{SS(PVSS)} = V _{SS(TVSS)} = 0V | 2.5 | 3.3 | 3.6 | V |
| V _{DDD} | digital supply voltage | V _{DD(PVDD)} ≤ V _{DDA} = V _{DDD} = V _{DD(TVDD)} , V _{SSA} = V _{SSD} = V _{SS(PVSS)} = V _{SS(TVSS)} = 0V | 2.5 | 3.3 | 3.6 | V |
| V _{DD(TVDD)} | TVDD supply voltage | V _{DD(PVDD)} ≤ V _{DDA} = V _{DDD} = V _{DD(TVDD)} , V _{SSA} = V _{SSD} = V _{SS(PVSS)} = V _{SS(TVSS)} = 0V | 2.5 | 3.3 | 3.6 | V |
| V _{DD(PVDD)} | PVDD supply voltage | V _{DD(PVDD)} ≤ V _{DDA} = V _{DDD} = V _{DD(TVDD)} , V _{SSA} = V _{SSD} = V _{SS(PVSS)} = V _{SS(TVSS)} = 0V | 1.6 | 1.8 | 3.6 | V |
| V _{DD(SVDD)} | SVDD supply voltage | V _{DD(PVDD)} ≤ V _{DDA} = V _{DDD} = V _{DD(TVDD)} , V _{SSA} = V _{SSD} = V _{SS(PVSS)} = V _{SS(TVSS)} = 0V | 1.6 | - | 3.6 | V |
| T _{amb} | ambient temperature | V _{DD(PVDD)} ≤ V _{DDA} = V _{DDD} = V _{DD(TVDD)} , V _{SSA} = V _{SSD} = V _{SS(PVSS)} = V _{SS(TVSS)} = 0V | -25 | - | +85 | °C |

9. Power Consumption

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-------------------|-------------------------|---|-----|-----|-----|------|
| I _{hp} | Hard power down current | V _{DDA} = V _{DDD} = V _{DD(TVDD)} = V _{DD(PVDD)} = 3V hard power down | - | 0.6 | - | uA |
| I _{sp} | Soft power down current | V _{DDA} = V _{DDD} = V _{DD(TVDD)} = V _{DD(PVDD)} = 3V soft power down | - | 3.4 | - | uA |
| I _{idle} | Idle mode current | V _{DDA} = V _{DDD} = V _{DD(TVDD)} = V _{DD(PVDD)} = 3V | | 7.7 | | mA |

10. Package Outline





BOTTOM VIEW
VIEW M-M

| | SYMBOL | MIN | NOM | MAX |
|------------------------|--------|-----------|-------|------|
| TOTAL THICKNESS | A | 0.8 | 0.85 | 0.9 |
| STAND OFF | A1 | 0 | 0.035 | 0.05 |
| MOLD THICKNESS | A2 | --- | 0.65 | --- |
| L/F THICKNESS | A3 | 0.203 REF | | |
| LEAD WIDTH | b | 0.2 | 0.25 | 0.3 |
| BODY SIZE | X | D | 5 BSC | |
| | Y | E | 5 BSC | |
| LEAD PITCH | e | 0.5 BSC | | |
| EP SIZE | X | J | 3.1 | 3.2 |
| | Y | K | 3.1 | 3.2 |
| LEAD LENGTH | L | 0.35 | 0.4 | 0.45 |
| PACKAGE EDGE TOLERANCE | aaa | 0.1 | | |
| MOLD FLATNESS | bbb | 0.1 | | |
| COPLANARITY | ccc | 0.08 | | |
| LEAD OFFSET | ddd | 0.1 | | |
| EXPOSED PAD OFFSET | eee | 0.1 | | |
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11. Ordering Information

| Part Number | Package |
|-------------|-----------|
| GT23SC55460 | QFN,32Pin |

12. Revision History

| REV | History | Page | Date |
|-----|-----------------|------|------------|
| 1.0 | Initial Version | 8 | 12/01/2013 |
| | | | |

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